



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

- 1.MATERIAL:
 HOUSING: PBT, BLACK, UL94V-0
 CONTACTS: 0.35[0.014] THICK PHOSPHOR BRONZE PLATED WITH 100 μ m MINIMUM THICK TIN LEAD IN SOLDER AREA. 15 μ m MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE CONTACTS PLATED WITH 50 μ m MINIMUM THICK NICKEL.
 SHIELDED: 0.25[0.0098] THICK COPPER ZINC ALLOY PLATED WITH 30 μ m MINIMUM THICK NICKEL.
- 2.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.



PART NO. MJF13UL-KF15B34F1-0808

DWG NO. MJF13UL-KF15B34F1-0808

CHECKED BY CY

TOLERANCES ARE

DESCRIP TION:

RJ45, MODULAR JACK,
1X1, W/O LED, 8P, 8C,
SHIELDED, THRU-HOLE

FILE NO.

DRAWING BY

.X \pm
 .XX \pm
 .XXX \pm
 AWG

AREA

REVISIONS

HK

DATE

煜倫有限公司

UNIT / mm

SCALE 1:1

PROJECTION

